Plastic Packages for Integrated Circuits

Package Outline Drawing

E18.3

18 LEAD DUAL-IN-LINE PLASTIC PACKAGE

Rev. 3, 11/11

NOTES:

1. Controlling Dimensions: INCH (Metric dimensions in parentheses).
3. Symbols are defined in the “MO Series Symbol List” in Section 2.2 of Publication No. 95.
4. Dimensions are measured with the package seated in JEDEC seating plane gauge GS-3.
5. Dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 inch (0.25mm).
6. Dimensions are measured with the leads constrained to be perpendicular to datum.
7. Dimension measured at the lead tips with the leads unconstrained.
8. Maximum dimensions do not include dambar protrusions. Dambar protrusions shall not exceed 0.010 inch (0.25mm).
9. Package outline compliant to JEDEC MS-001-AC ISSUE D.